



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	TLD5099EP	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005709051		
<b>Package</b>	PG-TSDSO-14-3	<b>Weight*</b>	61.24 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.325	3.80	3.80	37966	37966
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		135	
	non noble metal	zinc	7440-66-6	0.033	0.05		540	
	non noble metal	iron	7439-89-6	0.662	1.08		10804	
	non noble metal	copper	7440-50-8	26.866	43.88	45.02	438682	450161
wire	non noble metal	copper	7440-50-8	0.158	0.26	0.26	2576	2576
encapsulation	organic material	carbon black	1333-86-4	0.086	0.14		1411	
	plastics	epoxy resin	-	3.371	5.50		55040	
	inorganic material	silicondioxide	60676-86-0	25.353	41.40	47.04	413979	470430
leadfinish	non noble metal	tin	7440-31-5	1.451	2.37	2.37	23690	23690
plating	noble metal	silver	7440-22-4	0.160	0.26	0.26	2608	2608
glue	plastics	epoxy resin	-	0.192	0.31		3142	
	noble metal	silver	7440-22-4	0.577	0.94	1.25	9427	12569
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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